

## Dual 2:1 USB2.0 Mux/De-Mux

### DESCRIPTION

The FSW7222A is a bidirectional low-power dual port, high-speed, USB 2.0 analog switch with integrated protection for USB Type-C™ systems. The device is configured as a dual 2:1 or 1:2 switch. It is optimized for use with the USB 2.0 DP/DM lines in a USB Type-C™ system. GPIO controls of SEL and  $\overline{\text{EN}}$  are 1.8V logic compatible.

The FSW7222A is available in UQFN 1.4x.18-10L and MSOP10 with Pb-free and Halogen-free making it a perfect candidate for mobile and space constrained applications.

### FEATURES

- Supply Range 1.8 V to 5.5 V
- Differential 2:1 or 1:2 Switch/Multiplexer
- Low  $R_{\text{ON}}$  of 11  $\Omega$  Typical
- Low Crosstalk: -28dB @ 1GHz
- -3dB Bandwidth: 1.4GHz
- Off Isolation: -48dB @10MHz
- Break-Before-Make Switching
- Temperature Range of -40°C to 85°C

### APPLICATIONS

- Anywhere a USB Type-C™ or Micro-B Connector is Used
- USB 2.0 Signal Routing
- Digital Cameras and Camcorders
- Portable Instrumentation
- Set-Top Box
- PADS the withstand USB devices
- Mobile Phones, Tablets and Notebooks

## ORDER INFORMATION

Model	Package	Specified Temperature Range	Ordering Number	Packing Option
FSW7222A	UQFN 1.4x1.8-10L	-40°C to +85°C	FSW7222AYUWQ10G/TR	Tape and Reel, 3000
	MSOP10	-40°C to +85°C	FSW7222AYMS10G/TR	Tape and Reel, 3000

## PIN CONFIGURATION

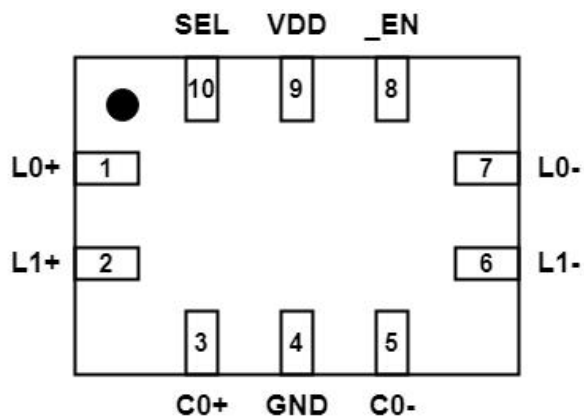


Figure 1. UQFN 1.4x1.8-10L

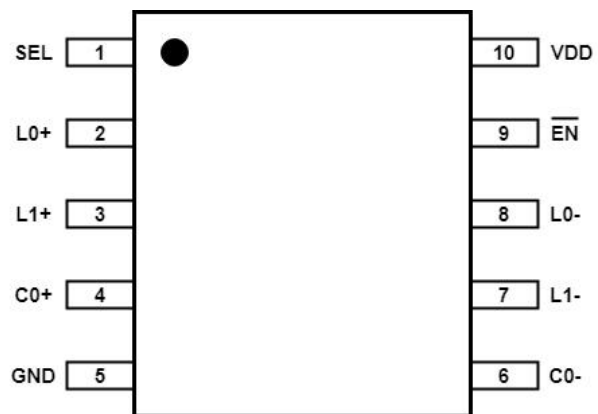


Figure 2. MSOP10

## PIN DESCRIPTION

UQFN1.4x1.8-10L	MSOP10	Pin Name	Signal Type	Description
3	4	C0+	I/O	Signal I/O, Common Port
5	6	C0-	I/O	Signal I/O, Common Port
2	3	L1+	I/O	Signal I/O, Channle 1
6	7	L1-	I/O	Signal I/O, Channle 1
1	2	L0+	I/O	Signal I/O, Channle 0
7	8	L0-	I/O	Signal I/O, Channle 0
10	1	SEL	I	Operation Model Select (when SEL=0: C0→L0, when SEL=1: C0→L1)
8	9	_EN	I	_EN=1, Power Down is Enabled
9	10	VDD	PWR	Positive Supply Voltage
4	5	GND	GND	Power Ground

## TRUTH TABLE

Function	SEL	_EN
C0+/- to L0+/-	L	L
C0+/- to L1+/-	H	L
All Switches Hi-Z	X	H

## Typical Application

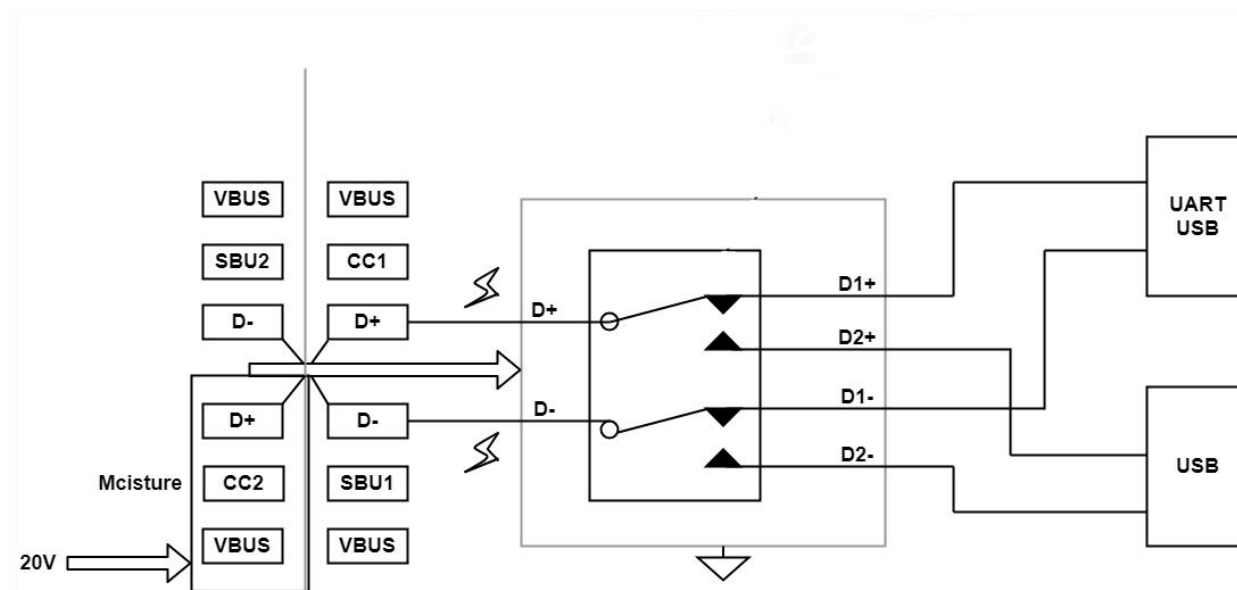


Figure 3. FSW7222A Application circuit

In addition, considering the power consumption requirements of portable products, FSW7222A is designed to minimize static power consumption. As shown in Figure 5 below, FSW7222A integrates pull-down resistance on both SEL and / OE pins. The weak pull-down resistance on the SEL pin saves power and ensures that channel 1 is opened in the default state, and the weak pull-down resistance on the OE pins ensures that the chip can work after power on.

## FUNCTIONAL DIAGRAM

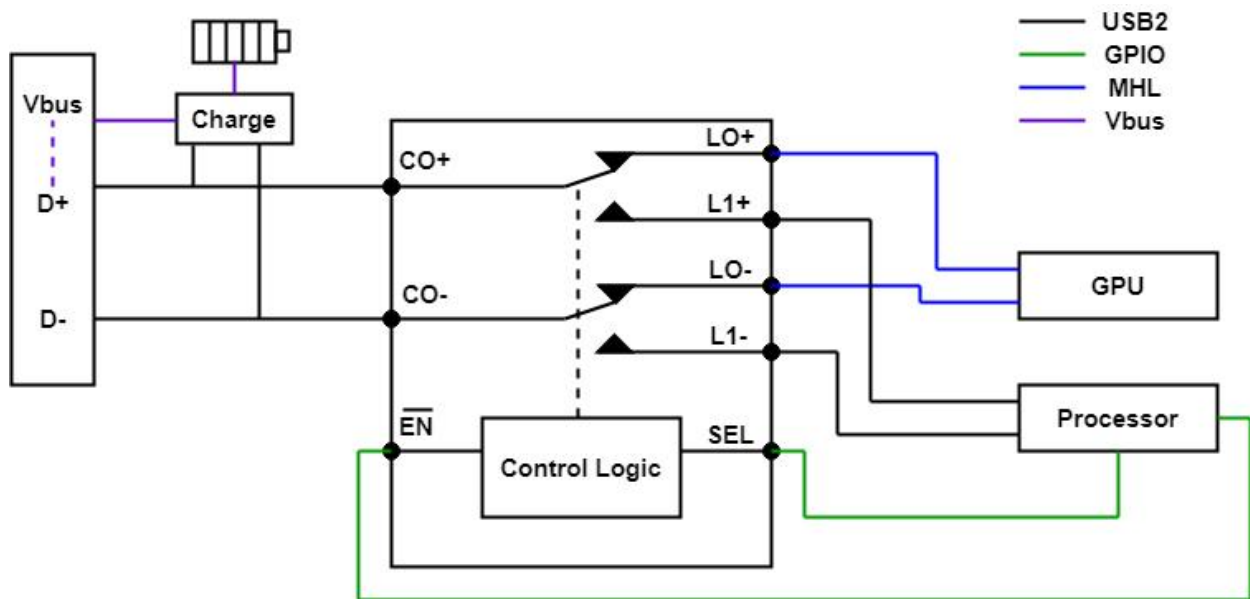


Figure 4. Function Diagram

FSW7222A is a high-speed, low-power double knife/double throw (DPDT) analog switch, supporting power supply from 1.8V to 5.5V. FSW7222A is designed to switch high-speed USB 2.0 signals in handheld devices (such as mobile phones, digital cameras, and laptops, with hubs or controllers).

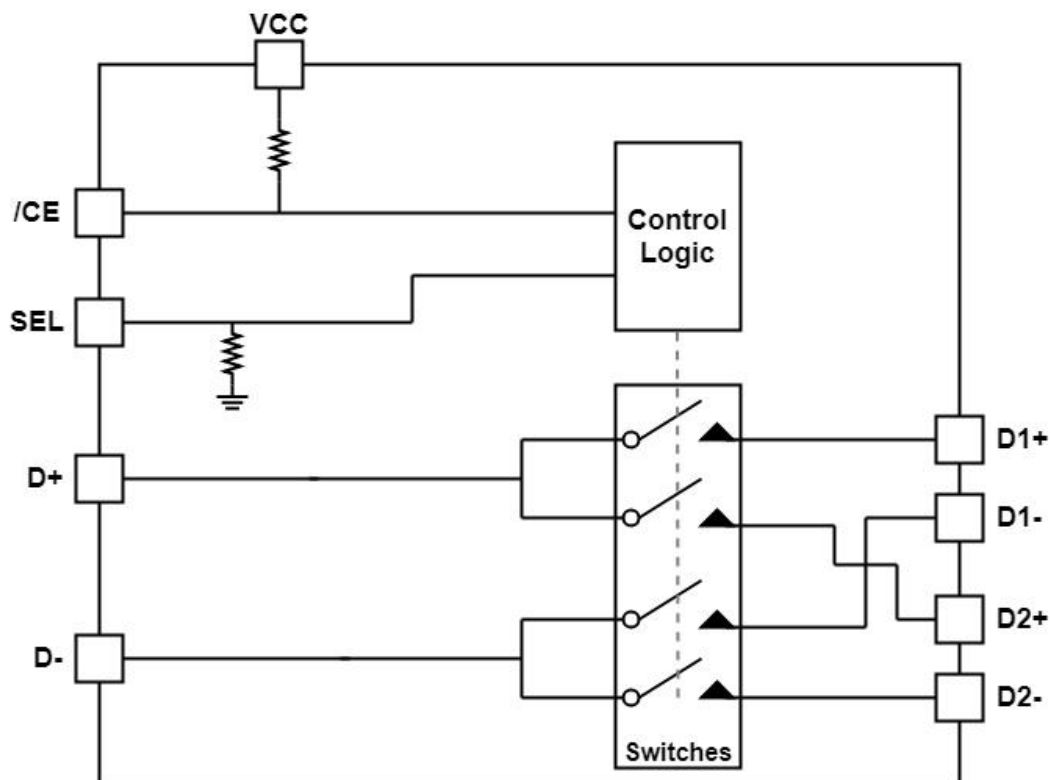


Figure 5. Internal function diagram

## ELECTRICAL CHARACTERISTICS

(T<sub>A</sub>=25°C, V<sub>DD</sub>=3.3V, unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
POWER SUPPLY						
Supply Voltage Range	V <sub>DD</sub>		1.8	3.3	5.5	V
Supply Current	I <sub>CC</sub>	_EN =1 disconnection, V <sub>DD</sub> =3.6V or 5.5V			1	uA
		_EN =0 connection, V <sub>DD</sub> =1.8V			15	
		_EN =0 connection, V <sub>DD</sub> =3.6V			18	
		_EN =0 connection, V <sub>DD</sub> =5.5V			30	
SEL/_EN DIGITAL INPUT CONTROL						
control input logic high	V <sub>IH</sub>	V <sub>DD</sub> =3.3V	1			V
		V <sub>DD</sub> =5.5V	1.3			V
control input logic low	V <sub>IL</sub>	V <sub>DD</sub> =3.3V			0.7	V
		V <sub>DD</sub> =5.5V			0.8	V
Control Input Leakage Current	I <sub>SEL</sub>	V <sub>DD</sub> =3.6V, V <sub>SEL</sub> =0.3V or 3.3V, V <sub>I/O</sub> =0V			1	uA
SWITCH ON RESISTANCE AND OFF LEAKAGE						
On-Resistance	R <sub>ON</sub>	V <sub>DD</sub> =3.3V, V <sub>C0+/-</sub> =0V~5.5V, I <sub>D</sub> =8mA, V <sub>SEL</sub> =0V or V <sub>DD</sub>		11	15	Ω
R <sub>ON</sub> Flatness <sup>(1)</sup>	R <sub>FLAT</sub>			0.05	1.45	Ω
R <sub>ON</sub> Matching Between Channels <sup>(2)</sup>	ΔR <sub>ON</sub>			0.23	1	Ω
Channel Off Leakage Current	I <sub>L0/L1</sub>	V <sub>DD</sub> =3.3V, V <sub>L0/L1</sub> =0.3V or 3.3V, V <sub>C0+/-</sub> = 0V, V <sub>SEL</sub> =0V or V <sub>DD</sub>			1	uA
Power OFF Leakage Current(C0+/C0-)	I <sub>OFF</sub>	V <sub>DD</sub> =3.3V, V <sub>C0+/-</sub> = 0.3V or 3.3V, V <sub>L0/L1</sub> =0V, V <sub>SEL</sub> =0V or V <sub>DD</sub>			1	uA
SWITCH DYNAMICS						
Off Isolation	O <sub>ISO</sub>	f = 10MHz, R <sub>L</sub> = 50Ω, Signal = -10dBm		-48		dB
		f = 500MHz, R <sub>L</sub> = 50Ω, Signal = -10dBm		-21		
Crosstalk <sup>(3)</sup> (Channel-to-Channel)	X <sub>TALK</sub>	f = 1GHz, R <sub>L</sub> = 50Ω, Signal = -10dBm		-28		dB
		f = 500MHz, R <sub>L</sub> = 50Ω, Signal = -10dBm		-54		
-3dB Bandwidth	BW	R <sub>L</sub> =50Ω, Signal = -10dBm		1.4		GHz
Break-Before-Make Delay Time	T <sub>BBM</sub>	V <sub>C0+/-</sub> = 0.4V, R <sub>L</sub> =300Ω, C <sub>L</sub> =10pF		7		us
Turn-on Time	t <sub>ON</sub>	V <sub>C0+/-</sub> = 0.4V, R <sub>L</sub> =300Ω, C <sub>L</sub> =10pF		1.6		us
Turn-off Time	t <sub>OFF</sub>	V <sub>C0+/-</sub> = 0.4V, R <sub>L</sub> =300Ω, C <sub>L</sub> =10pF		70		ns

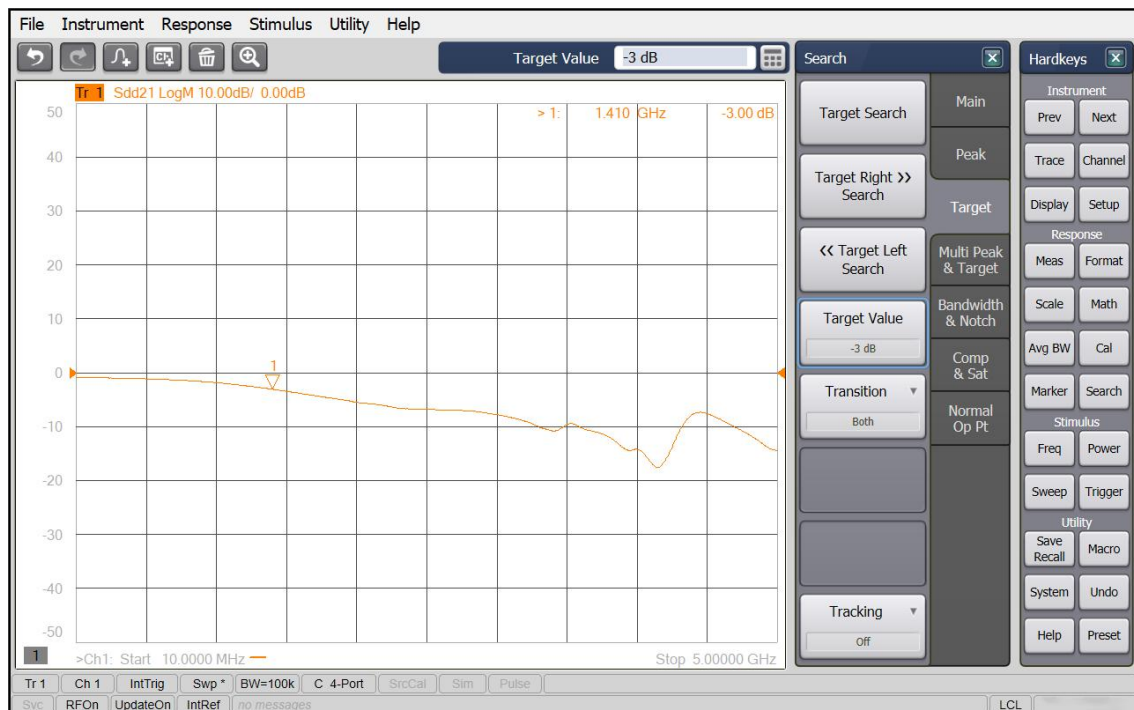
Note:

(1) Flatness is defined as the difference between maximum and minimum value of ON-resistance at the specified analog signal voltage points.

- (2)  $R_{ON}$  matching between channels is calculated by subtracting the channel with the lowest max  $R_{on}$  value from the channel with the highest max  $R_{on}$  value.
- (3) Crosstalk is inversely proportional to source impedance

## TYPICAL PERFORMANCE CURVES

$T_A=25^{\circ}\text{C}$ ,  $V_{DD}=3.3\text{V}$ , unless otherwise noted



**Fig 7. Switch Bandwidth**

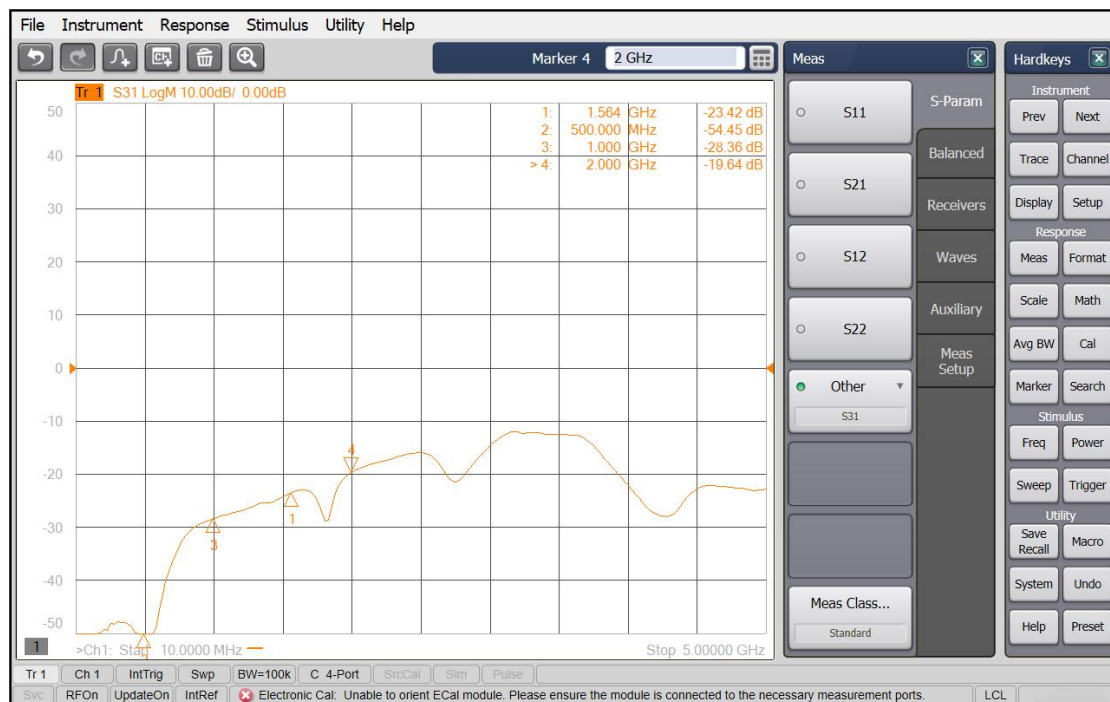


Fig 8. Switch Cross-Talk

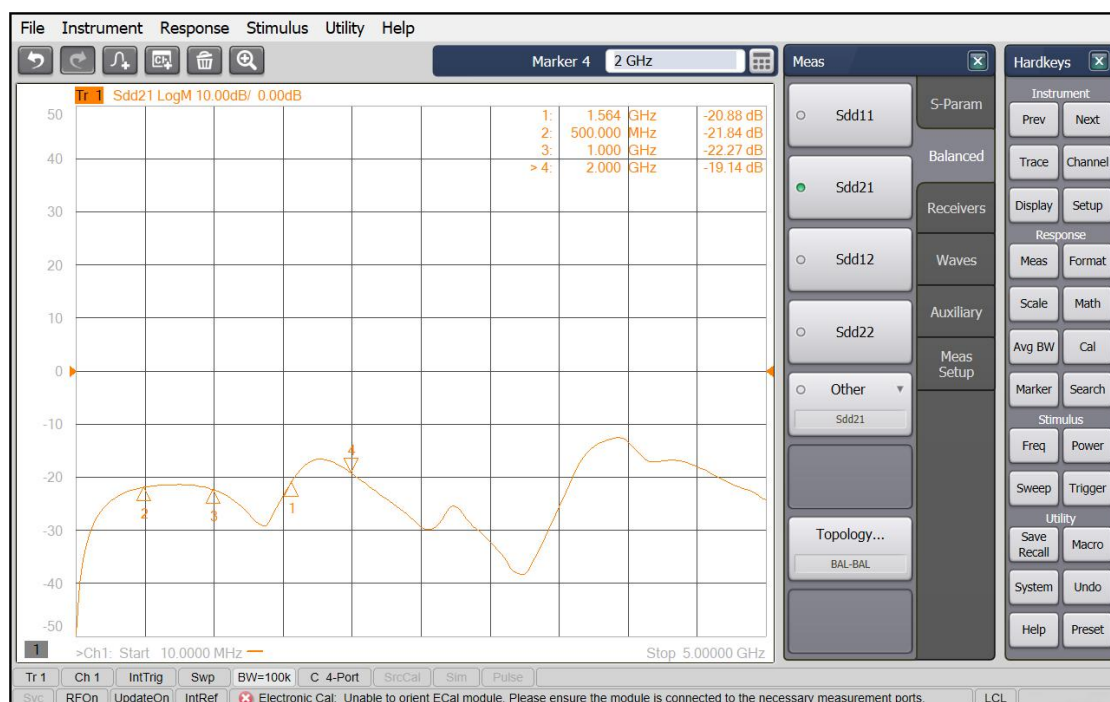
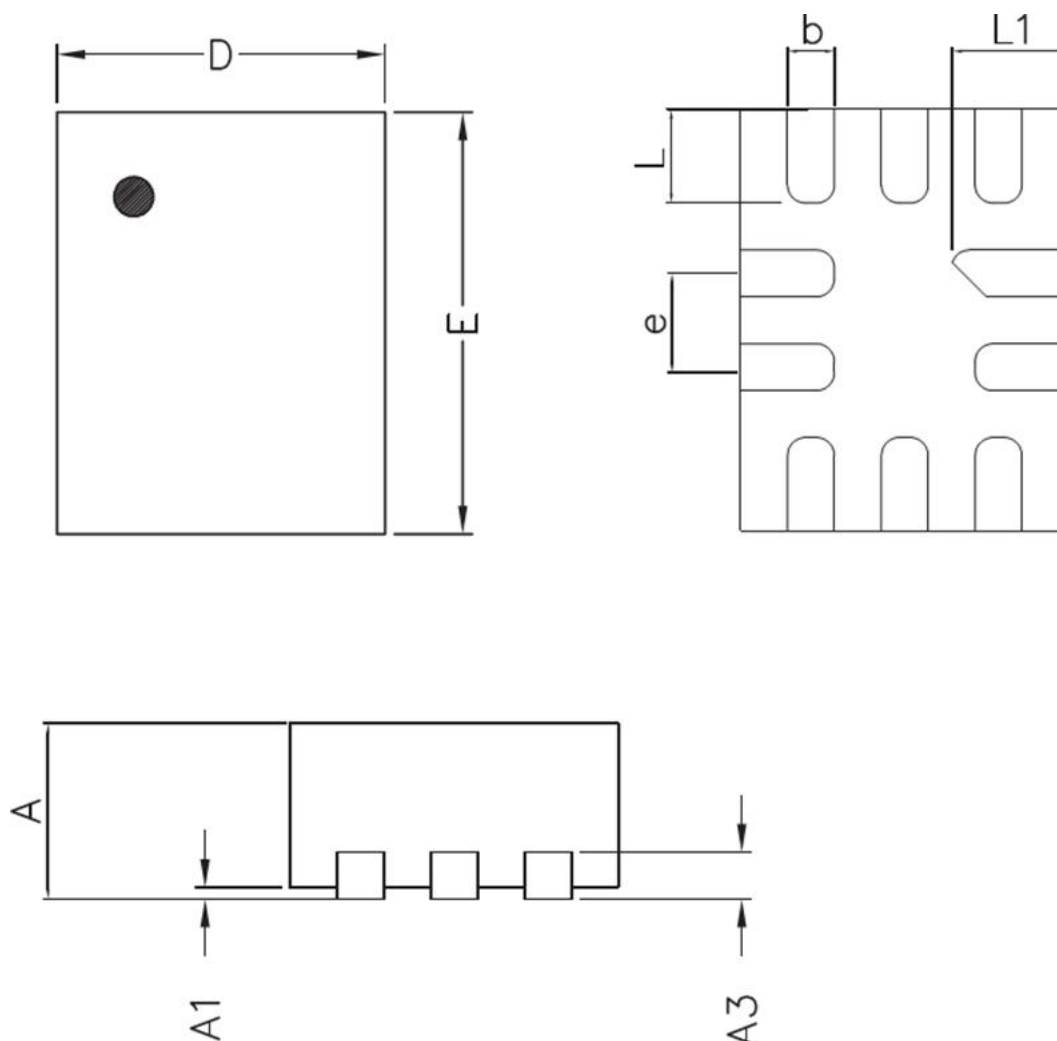


Fig 9. Switch Off Isolation

## PACKAGE OUTLINE DIMENSIONS(All dimensions in mm.)

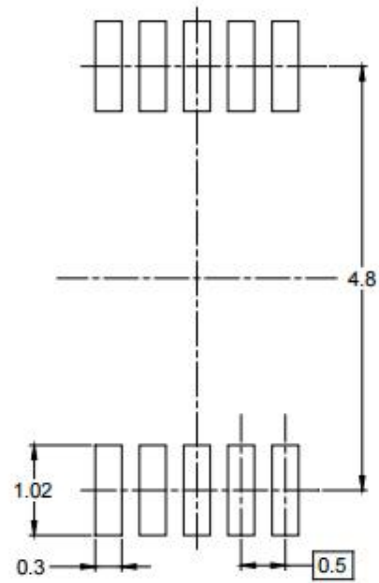
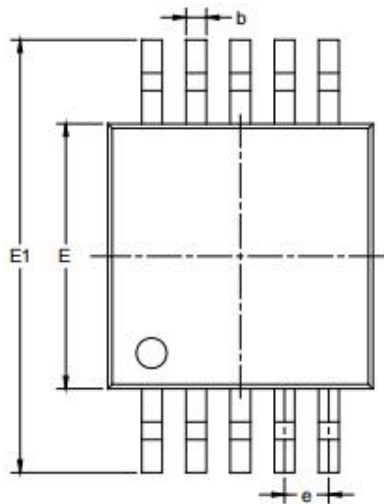
(1) Package Type: UQFN 1.4x1.8 -10L



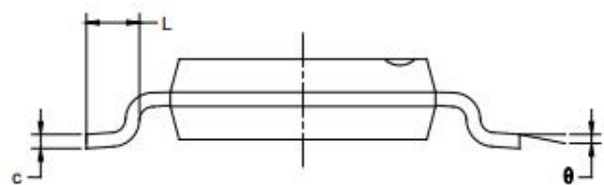
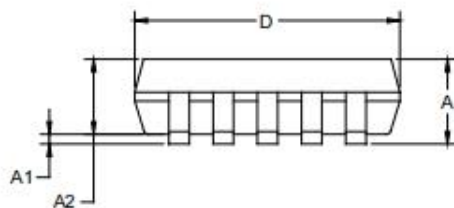
Symbol	Dimension in Millimeters	
	Min.	Max.
A	0.450	0.550
A1	0.000	0.050
A3	0.152 Ref.	
D	1.350	1.450
E	1.750	1.850
b	0.150	0.250
e	0.400 Typ.	
L	0.350	0.450
L1	0.450	0.550

(2) Package Type: MSOP10





RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.180	0.280	0.007	0.011
c	0.090	0.230	0.004	0.009
D	2.900	3.100	0.114	0.122
E	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
e	0.500BSC		0.020BSC	
L	0.400	0.800	0.016	0.031
$\theta$	0°	6°	0°	6°

## Important Notice And Disclaimer

- We reserves the right to change the instruction manual without prior notice.
- Any semiconductor product has a certain possibility of failure or malfunction under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design and overall manufacturing to avoid potential failure risks that may cause personal injury or property damage.
- The improvement of product quality is endless, our company will be dedicated to provide customers with better products.

## Version Modification Record

Version Number	Revision
first edition	
V1.0	1. Update the ELECTRICAL CHARACTERISTICS on page 5.